

Tape Specifications

Dicing Tape Non-UV Type

Part Number	Base Film	Color	Base Film Thickness (μm)	Adhesion Thickness (μm)	Adhesive Strength (N/20 mm)	Probe-Tack (N/20 mm ²)	Applications	Feature
F-90MW	PO	MW	90	10	1.0	1.0	Si wafer GaAs and others	PVC free type
T-80MW	PVC	MW	80	10	0.8	0.7	Si wafer GaAs and others	
T-80HW	PVC	MW	80	10	1.7	1.0	Si wafer GaAs and others	
T-120HW	PVC	MW	120	10	1.7	1.0	Si wafer GaAs and others	

Dicing Tape UV Type

Part Number	Base Film	Color	Thickness (μm)	Adhesion Thickness (μm)	Adhesive Strength (N/20 mm)	Probe-Tack (N/20 mm ²)	Applications	Feature
UDV-80J	PVC	T	80	10	3.8(0.2)	2.1(0.10)	Silicon (Si), gallium arsenide (GaAs) and other types of semi-conductors	For Easy pickup
UDV-100J			100		3.8(0.2)	2.1(0.10)		
UHP-0805MC	PO	MW	85	5	5.0(0.2)	1.7(0.05)		Limits amount of chipping and cracks on the backside surface
UHP-1005M3			105		3.5(0.2)	2.2(0.05)		

UHP-1005AT			105		2.2(0.1)	1.7(0.05)		
UHP-110AT			110		2.8(0.1)	2.2(0.05)		Exhibits excellent pickup
UHP-110BZ			110	10	2.9(0.1)	2.7(0.05)		
UHP-110M3			110		5.6(0.2)	3.8(0.05)		Compatible with small-sized chips
UHP-1025M3			125	25	12.0(0.2)	5.5(0.05)		
UHP-1510M3			160	10	6.5(0.2)	4.2(0.05)		Compatible with workpieces that are incredibly anti-adhesive
USP-1510M4			160		10.0(0.2)	4.4(0.05)		Prevents burrs from forming on the backside surface
UHP-1515M3			165		10.5(0.2)	4.6(0.05)	Package substrate (BGA/QFN etc)	Prevents the side of die from residue caused by scratched adhesive
USP-1515M4		165	15	14.5(0.2)	6.2(0.05)			Limits the amount of residue buildup on the marking area
UHP-1515K			165		8.6(0.2)	3.9(0.05)		
USP-1520MG			170	20	17.0(0.2)	7.0(0.05)		

UHP-1525M3			175	25	13.0(0.2)	5.6(0.05)		
UDT-1005M3	PET	T	105	5	4.8(0.1)	3.6(0.05)	Glass, crystal	Limits the amount of chipping and cracks on the backside surface
UDT-1025MC			125		29.0(0.2)	7.5(0.05)		
UDT-1325D			150	25	22.0(0.2)	6.7(0.05)		Compatible with work-pieces that are incredibly anti-adhesive
UDT-1915MC			203	15	20.0(0.2)	5.9(0.05)		Limits the amount of chipping and cracks on the backside surface